

SEMICONDUCTOR DEVICE PROTECTIVE STRUCTURE AND METHOD FOR FABRICATING THE SAME

ABSTRACT OF THE INVENTION

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The present invention provides a semiconductor device protective structure. The structure comprises a die with contact metal balls formed thereon electrically coupling with a print circuit board. A back surface of the die is directly adhered on a substrate and a first buffer layer is formed on the substrate. The substrate is configured over a
10 second buffer layer such that the second buffer layer substantially encompasses the whole substrate to decrease damage to the substrate when the side of the substrate is collided with an external object.

15 FIG. 2